



General Description

The MAX1473 fully integrated low-power CMOS superheterodyne receiver is ideal for receiving amplitudeshift-keyed (ASK) data in the 300MHz to 450MHz frequency range. Its signal range is from -114dBm to 0dBm. With few external components and a low-current power-down mode, it is ideal for cost- and power-sensitive applications typical in the automotive and consumer markets. The chip consists of a low-noise amplifier (LNA), a fully differential image-rejection mixer, an onchip phase-locked-loop (PLL) with integrated voltagecontrolled oscillator (VCO), a 10.7MHz IF limiting amplifier stage with received-signal-strength indicator (RSSI), and analog baseband data-recovery circuitry. The MAX1473 also has a discrete one-step automatic gain control (AGC) that drops the LNA gain by 35dB when the RF input signal is greater than -57dBm.

The MAX1473 is available in 28-pin TSSOP and 32-pin thin QFN packages. Both versions are specified for the extended (-40°C to +85°C) temperature range.

Applications

Automotive Remote Keyless Entry Garage Door Openers Remote Controls Wireless Sensors Security Systems
Home Automation
Local Telemetry
Systems

Features

- ♦ Optimized for 315MHz or 433MHz ISM Band
- ♦ Operates from Single 3.3V or 5.0V Supplies
- ♦ High Dynamic Range with On-Chip AGC
- **♦** Selectable Image-Rejection Center Frequency
- ♦ Selectable x64 or x32 fLO/fxTAL Ratio
- **♦ Low 5.2mA Operating Supply Current**
- ♦ < 2.5µA Low-Current Power-Down Mode for Efficient Power Cycling
- ♦ 250µs Startup Time
- ♦ Built-In 50dB RF Image Rejection
- ♦ Receive Sensitivity of -114dBm

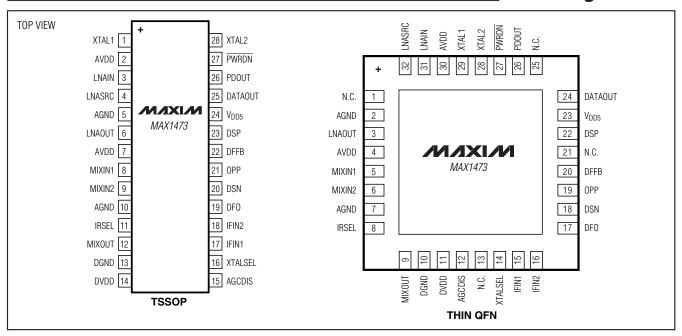
Ordering Information

| PART | TEMP RANGE | PIN-PACKAGE |
|-------------|----------------|-----------------|
| MAX1473EUI+ | -40°C to +85°C | 28 TSSOP |
| MAX1473ETJ+ | -40°C to +85°C | 32 Thin QFN-EP* |

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

Functional Diagram and Typical Application Circuit appear at end of data sheet.

Pin Configurations



Maxim Integrated Products

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For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

^{*}EP = Exposed pad.

ABSOLUTE MAXIMUM RATINGS

| V _{DD5} to AGND0.3V to +6.0 | V Continuous Power |
|---|----------------------|
| AVDD to AGND0.3V to +4.0 | V 28-Pin TSSOP (|
| DVDD to DGND0.3V to +4.0 | V 32-Pin Thin QFN |
| AGND to DGND0.1V to +0.1 | V above +70°C) |
| IRSEL, DATAOUT, XTALSEL, AGCDIS, | Operating Tempera |
| PWRDN to AGND0.3V to (V _{DD5} + 0.3V | V) MAX1473E |
| All Other Pins to AGND0.3V to (V _{DD} + 0.3V | V) Storage Temperatu |
| | Lead Temperature |

| Continuous Power Dissipation (T _A = +70° | C) |
|---|---------------------|
| 28-Pin TSSOP (derate 12.8mW/°C abo | ve +70°C) .1025.6mW |
| 32-Pin Thin QFN (derate 21.3mW/°C | |
| above +70°C) | 1702.1mW |
| Operating Temperature Ranges | |
| MAX1473E | 40°C to +85°C |
| Storage Temperature Range | 60°C to +150°C |
| | |
| Soldering Temperature (reflow) | +260°C |
| Operating Temperature Ranges MAX1473E | |

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS (3.3V OPERATION)

(Typical Application Circuit, $V_{DD} = 3.0V$ to 3.6V, no RF signal applied, $T_A = -40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Typical values are at $V_{DD} = 3.3V$ and $T_A = +25^{\circ}C$.) (Note 1)

| PARAMETER | SYMBOL | CONDITIONS | | MIN | TYP | MAX | UNITS |
|------------------------------|---|---|---------------------------|-----------------------|-----|-----------------------|-------|
| Supply Voltage | V_{DD} | 3.3V nominal sup | pply | 3.0 | 3.3 | 3.6 | V |
| Supply Current | las | \/ ===== \/== | f _{RF} = 315MHz | | 5.2 | 6.23 | m ^ |
| Supply Current | lDD | V _{PWRDN} = V _{DD} | $f_{RF} = 433MHz$ | | 5.8 | 6.88 | mA |
| Chutdown Cupply Current | l= | $V_{\overline{PWRDN}} = 0V,$ | $f_{RF} = 315MHz$ | | 1.6 | | |
| Shutdown Supply Current | PWRDN | VXTALSEL = 0V | $f_{RF} = 433MHz$ | | 2.5 | 5.3 | μΑ |
| Input Voltage Low | V _{IL} | | | | | 0.4 | V |
| Input Voltage High | VIH | | | V _{DD} - 0.4 | | | V |
| Input Logic Current High | lін | | | | 10 | | μΑ |
| | | f _{RF} = 433MHz, V | RSEL = VDD | | | V _{DD} - 0.4 | |
| Image Reject Select (Note 2) | Image Reject Select (Note 2) f _{RF} = 375MHz, V _{IRSEL} | | RSEL = V _{DD} /2 | 1.1 | | V _{DD} - 1.5 | V |
| | | f _{RF} = 315MHz, V _{IRSEL} = 0V | | 0.4 | | | |
| DATAOUT Voltage Output Low | V _{OL} | $R_L = 5k\Omega$ | | | | 0.4 | V |
| DATAOUT Voltage Output High | VoH | | | V _{DD} - 0.4 | | | V |

_ /N/IXI/N

DC ELECTRICAL CHARACTERISTICS (5.0V OPERATION)

(*Typical Application Circuit*, $V_{DD} = 4.5V$ to 5.5V, no RF signal applied, $T_A = -40^{\circ}$ C to $+85^{\circ}$ C, unless otherwise noted. Typical values are at $V_{DD} = 5.0V$ and $T_A = +25^{\circ}$ C.) (Note 1)

| PARAMETER | SYMBOL | CONDITIONS | | MIN | TYP | MAX | UNITS |
|------------------------------|-------------------|---|--------------------------|-----------------------|-----|-----------------------|-------|
| Supply Voltage | V_{DD} | 5.0V nominal sup | pply | 4.5 | 5.0 | 5.5 | V |
| Consolir Comment | 1 | \/= | f _{RF} = 315MHz | | 5.2 | 6.04 | A |
| Supply Current | IDD | $V_{\overline{PWRDN}} = V_{\overline{DD}}$ | $f_{RF} = 433MHz$ | | 5.7 | 6.76 | mA |
| Charteleum Campha Campant | I= | | $f_{RF} = 315MHz$ | | 2.3 | | ^ |
| Shutdown Supply Current | PWRDN | VXTALSEL = 0V | $f_{RF} = 433MHz$ | | 2.8 | 6.2 | μΑ |
| Input Voltage Low | VIL | | | | | 0.4 | V |
| Input Voltage High | VIH | | | V _{DD} - 0.4 | | | V |
| Input Logic Current High | lін | | | | 10 | | μΑ |
| | | $f_{RF} = 433MHz, V$ | IRSEL = V _{DD} | | | V _{DD} - 0.4 | |
| Image Reject Select (Note 2) | | f _{RF} = 375MHz, V _{IRSEL} = V _{DD} /2 | | 1.1 | | V _{DD} - 1.5 | V |
| $f_{RF} = 3$ | | f _{RF} = 315MHz, V | IRSEL = 0V | 0.4 | | | |
| DATAOUT Voltage Output Low | V _{OL} | D. Sko | | | | 0.4 | V |
| DATAOUT Voltage Output High | VoH | | $R_L = 5k\Omega$ | | | | V |

AC ELECTRICAL CHARACTERISTICS

(Typical Application Circuit, $V_{DD}=3.0V$ to 3.6V, all RF inputs are referenced to 50Ω , $f_{RF}=315MHz$, $T_A=-40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Typical values are at $V_{DD}=3.3V$ and $T_A=+25^{\circ}C$.) (Note 1).

| PARAMETER | SYMBOL | CONDITIONS | | MIN | TYP | MAX | UNITS |
|---------------------------------------|---------------------|--|-------------------|------|----------|---------|-------|
| GENERAL CHARACTERISTICS | | | | | | | |
| Startup Time | ton | Time for valid signal detection after VPWRDN = VOH | | | 250 | | μs |
| Receiver Input Frequency | f _{RF} | | | 300 | | 450 | MHz |
| Maximum Receiver Input Level | PRFIN_MAX | Modulation dept | h > 18dB | | 0 | | dBm |
| Consitiuity (Note 2) | Dogue | Average carrier | power level | | -120 | | dBm |
| Sensitivity (Note 3) | PRFIN_MIN | Peak power leve | | -114 | |] ubiii | |
| ACC Hyptoropia | | LNA gain from lo | w to high | | 8 | | dB |
| AGC Hysteresis | | LINA Gaill Iroin ic | w to riigir | | 150 | | ms |
| LNA IN HIGH-GAIN MODE | | | | | | | |
| Power Gain | | | | | 16 | | dB |
| | | | $f_{RF} = 433MHz$ | | 1 - j3.4 | | |
| Input Impedance | Z _{IN_LNA} | Normalized to 50Ω (Note 4) | $f_{RF} = 375MHz$ | | 1 - j3.9 | | |
| | | 50 22 (Note 4) | $f_{RF} = 315MHz$ | | 1 - j4.7 | | |
| 1dB Compression Point | P1dB _{LNA} | | | | -22 | | dBm |
| Input-Referred 3rd-Order Intercept | IIP3 _{LNA} | | | | -12 | | dBm |



AC ELECTRICAL CHARACTERISTICS (continued)

(Typical Application Circuit, $V_{DD}=3.0V$ to 3.6V, all RF inputs are referenced to 50Ω , $f_{RF}=315MHz$, $T_{A}=-40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Typical values are at $V_{DD}=3.3V$ and $T_{A}=+25^{\circ}C$.) (Note 1)

| PARAMETER | SYMBOL | CONDITIONS | | MIN | TYP | MAX | UNITS |
|---|----------------------|---|--------------------------|-----|----------|-----|-------|
| LO Signal Feedthrough to Antenna | | | | | -80 | | dBm |
| Noise Figure | NF _{LNA} | | | | 2 | | dB |
| LNA IN LOW-GAIN MODE | | | | | | | |
| | | | f _{RF} = 433MHz | | 1 - j3.4 | | |
| Input Impedance (Note 4) | Z _{IN_LNA} | Normalized to 50Ω | $f_{RF} = 375MHz$ | | 1 - j3.9 | | |
| | | 5052 | $f_{RF} = 315MHz$ | | 1 - j4.7 | | |
| 1dB Compression Point | P1dB _{LNA} | | | | -10 | | dBm |
| Input-Referred 3rd-Order Intercept | IIP3 _{LNA} | | | | -7 | | dBm |
| LO Signal Feedthrough to Antenna | | | | | -80 | | dBm |
| Noise Figure | NF _{LNA} | | | | 2 | | dB |
| Power Gain | | | | | 0 | | dB |
| Voltage Gain Reduction | | AGC enabled (de | epends on tank Q) | | 35 | | dB |
| MIXER | <u>.</u> | | | | | | • |
| Input-Referred 3rd-Order Intercept | IIP3 _{MIX} | | | | -18 | | dBm |
| Output Impedance | Z _{OUT_MIX} | | | | 330 | | Ω |
| Noise Figure | NF _{MIX} | | | | 16 | | dB |
| | | f _{RF} = 433MHz, V | IRSEL = VDD | | 42 | | |
| Image Rejection (not Including LNA Tank) | | f _{RF} = 375MHz, V _{IRSEL} = V _{DD} /2 | | | 44 | | dB |
| (HOLINCIAGING LIVA TANK) | | $f_{RF} = 315MHz, V$ | | | 44 | | 1 |
| Conversion Gain | | 330Ω IF filter load | d | | 13 | | dB |
| INTERMEDIATE FREQUENCY | Y (IF) | | | | | | |
| Input Impedance | Z _{IN_IF} | | | | 330 | | Ω |
| Operating Frequency | fiF | Bandpass respo | nse | | 10.7 | | MHz |
| 3dB Bandwidth | | | | | 20 | | MHz |
| RSSI Linearity | | | | | ±0.5 | | dB |
| RSSI Dynamic Range | | | | | 80 | | dB |
| RSSI Level | | P _{RFIN} < -120dBr | n | | 1.15 | | V |
| NOOI LEVEI | | P _{RFIN} > 0dBm, A | AGC enabled | | 2.35 | | |
| RSSI Gain | | | | | 14.2 | | mV/dB |
| AGC Threshold | | LNA gain from lo | w to high | | 1.45 | | V |
| Ado Illiestidia | | LNA gain from h | igh to low | | 2.05 | | V |

! ______ /V/X//M

AC ELECTRICAL CHARACTERISTICS (continued)

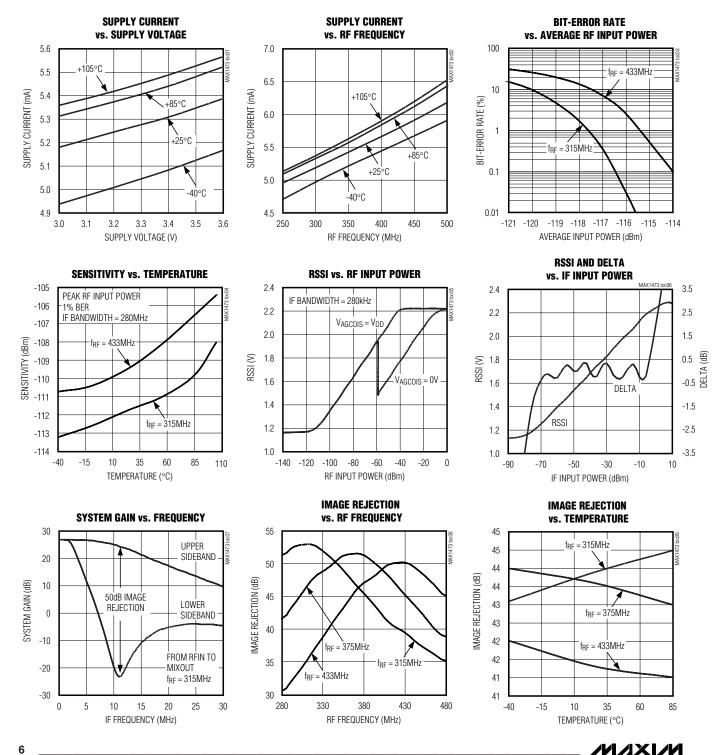
(*Typical Application Circuit*, $V_{DD} = 3.0V$ to 3.6V, all RF inputs are referenced to 50Ω , $f_{RF} = 315MHz$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Typical values are at $V_{DD} = 3.3V$ and $T_A = +25^{\circ}C$.) (Note 1)

| PARAMETER | SYMBOL | CONDITIONS | | MIN | TYP | MAX | UNITS |
|----------------------------|------------------|-------------------------|--|-----|-----------|--------|-------|
| DATA FILTER | | | | | | | |
| Maximum Bandwidth | BW _{DF} | | | | 100 | | kHz |
| DATA SLICER | | | | | | | |
| Comparator Bandwidth | BWcmp | | | | 100 | | kHz |
| Maximum Load Capacitance | CLOAD | | | | 10 | | рF |
| Output High Voltage | | | | | V_{DD5} | | V |
| Output Low Voltage | | | | | 0 | | V |
| CRYSTAL OSCILLATOR | | | | | | | |
| | | f 400MLI- | VXTALSEL = 0V | | 6.6128 | | NALI- |
| Crystal Fraguency (Note F) | f | $f_{RF} = 433MHz$ | V _{XTALSEL} = V _{DD} | | 13.2256 | | MHz |
| Crystal Frequency (Note 5) | fXTAL | f O1EMU¬ | VXTALSEL = 0V | | 4.7547 | | MHz |
| | | $f_{RF} = 315MHz$ | VXTALSEL = VDD | | 9.5094 | IVIFIZ | |
| Crystal Tolerance | | | | | 50 | • | ppm |
| Input Impedance | | From each pin to ground | | | 6.2 | | pF |

- Note 1: 100% tested at T_A = +25°C. Guaranteed by design and characterization over temperature.
- Note 2: IRSEL is internally set to 375MHz IR mode. It can be left open when the 375MHz image rejection setting is desired. A 1nF capacitor is recommended in noisy environments.
- Note 3: BER = 2 x 10-3, Manchester encoded, data rate = 4kbps, IF bandwidth = 280kHz.
- **Note 4:** Input impedance is measured at the LNAIN pin. Note that the impedance includes the 15nH inductive degeneration connected from the LNA source to ground. The equivalent input circuit is 50Ω in series with 2.2pF.
- Note 5: Crystal oscillator frequency for other RF carrier frequency within the 300MHz to 450MHz range is (f_{RF} 10.7MHz)/64 for XTALSEL = 0V, and (f_{RF} 10.7MHz)/32 for XTALSEL = V_{DD}.

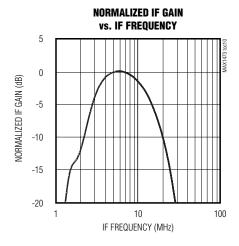
Typical Operating Characteristics

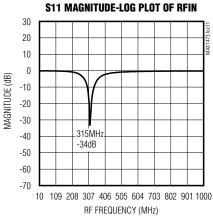
(Typical Application Circuit, VDD = 3.3V, fRF = 315MHz, TA = +25°C, unless otherwise noted.)

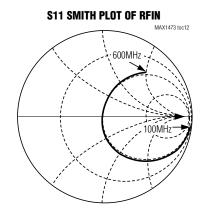


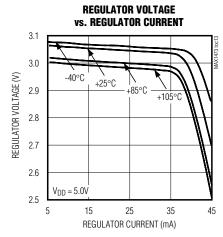
Typical Operating Characteristics (continued)

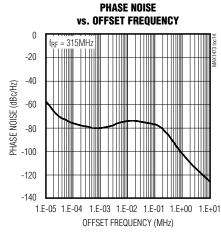
(*Typical Application Circuit*, V_{DD} = 3.3V, f_{RF} = 315MHz, T_A = +25°C, unless otherwise noted.)

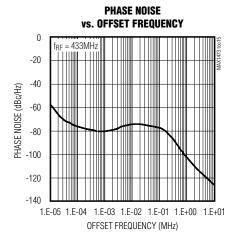












Pin Description

| PI | PIN | | FUNCTION | | | |
|-------|------------------|------------------|--|--|--|--|
| TSSOP | TQFN | NAME | FUNCTION | | | |
| 1 | 29 | XTAL1 | 1st Crystal Input. (See the <i>Phase-Locked Loop</i> section.) | | | |
| 2, 7 | 4, 30 | AVDD | Positive Analog Supply Voltage. For +5V operation, pin 2 is the output of an on-chip +3.2V low-dropout regulator and should be bypassed to AGND with a 0.1µF capacitor as close as possible to the pin. Pin 7 must be externally connected to the supply from pin 2 and bypassed to AGND with a 0.01µF capacitor as close as possible to the pin (see the <i>Voltage Regulator</i> section and the <i>Typical Application Circuit</i>). | | | |
| 3 | 31 | LNAIN | Low-Noise Amplifier Input. (See the Low-Noise Amplifier section.) | | | |
| 4 | 32 | LNASRC | Low-Noise Amplifier Source for External Inductive Degeneration. Connect inductor to ground to set LNA input impedance. (See the <i>Low-Noise Amplifier</i> section.) | | | |
| 5 | 2 | AGND | Analog Ground | | | |
| 6 | 3 | LNAOUT | Low-Noise Amplifier Output. Connect to mixer through an LC tank filter. (See the <i>Low-Noise Amplifier</i> section.) | | | |
| 8 | 5 | MIXIN1 | 1st Differential Mixer Input. Connect through a 100pF capacitor to V _{DD3} side of the LC tank. | | | |
| 9 | 6 | MIXIN2 | 2nd Differential Mixer Input. Connect through a 100pF capacitor to LC tank filter from LNAOUT. | | | |
| 10 | 7 | AGND | Analog Ground | | | |
| 11 | 8 | IRSEL | Image Rejection Select Pin. Set V _{IRSEL} = 0V to center image rejection at 315MHz. Leave IRSEL unconnected to center image rejection at 375MHz. Set V _{IRSEL} = V _{DD} to center image rejection at 433MHz. | | | |
| 12 | 9 | MIXOUT | 330Ω Mixer Output. Connect to the input of the 10.7MHz bandpass filter. | | | |
| 13 | 10 | DGND | Digital Ground | | | |
| 14 | 11 | DVDD | Positive Digital Supply Voltage. Connect to both of the AVDD pins. Bypass to DGND with a 0.01µF capacitor as close as possible to the pin (see the <i>Typical Application Circuit</i>). | | | |
| 15 | 12 | AGCDIS | AGC Control Pin. Pull high to disable AGC. | | | |
| 16 | 14 | XTALSEL | Crystal Divider Ratio Select Pin. Drive XTALSEL low to select divider ratio of 64, or drive XTALSEL high to select divider ratio of 32. | | | |
| 17 | 15 | IFIN1 | 1st Differential Intermediate Frequency Limiter Amplifier Input. Decouple to AGND with a 1500pF capacitor. | | | |
| 18 | 16 | IFIN2 | 2nd Differential Intermediate Frequency Limiter Amplifier Input. Connect to the output of a 10.7MHz bandpass filter. | | | |
| 19 | 17 | DFO | Data Filter Output | | | |
| 20 | 18 | DSN | Negative Data Slicer Input | | | |
| 21 | 19 | OPP | Noninverting Op-Amp Input for the Sallen-Key Data Filter | | | |
| 22 | 20 | DFFB | Data Filter Feedback Node. Input for the feedback of the Sallen-Key data filter. | | | |
| 23 | 22 | DSP | Positive Data Slicer Input | | | |
| 24 | 23 | V _{DD5} | +5V Supply Voltage. Bypass to AGND with a 0.01µF capacitor as close as possible to the pin. For +5V operation, V _{DD5} is the input to an on-chip voltage regulator whose +3.2V output appears at the pin 2 AVDD pin. (See the <i>Voltage Regulator</i> section and the <i>Typical Application Circuit</i> .) | | | |
| 25 | 24 | DATAOUT | Digital Baseband Data Output | | | |
| 26 | 26 | PDOUT | Peak Detector Output | | | |
| 27 | 27 | PWRDN | Power-Down Select Input. Drive this pin with a logic high to power on the IC. | | | |
| 28 | 28 | XTAL2 | 2nd Crystal Input | | | |
| | 1, 13, 21, 25 | N.C. | No Connection | | | |
| | _ | EP | Exposed Pad (TQFN Only). Connect EP to GND. | | | |

3 ______*MIXIM*

Detailed Description

The MAX1473 CMOS superheterodyne receiver and a few external components provide the complete receive chain from the antenna to the digital output data. Depending on signal power and component selection, data rates as high as 100kbps can be achieved.

The MAX1473 is designed to receive binary ASK data modulated in the 300MHz to 450MHz frequency range. ASK modulation uses a difference in amplitude of the carrier to represent logic 0 and logic 1 data.

Voltage Regulator

For operation with a single +3.0V to +3.6V supply voltage, connect AVDD, DVDD, and VDD5 to the supply voltage. For operation with a single +4.5V to +5.5V supply voltage, connect VDD5 to the supply voltage. An on-chip voltage regulator drives one of the AVDD pins to approximately +3.2V. For proper operation, DVDD and both the AVDD pins must be connected together. Bypass VDD5, DVDD, and the pin 7 AVDD pin to AGND with $0.01\mu F$ capacitors, and the pin 2 AVDD pin to AGND with a $0.1\mu F$ capacitor, all placed as close as possible to the pins.

Low-Noise Amplifier

The LNA is an NMOS cascode amplifier with off-chip inductive degeneration that achieves approximately 16dB of power gain with a 2.0dB noise figure and an IIP3 of -12dBm. The gain and noise figure are dependent on both the antenna matching network at the LNA input and the LC tank network between the LNA output and the mixer inputs.

The off-chip inductive degeneration is achieved by connecting an inductor from LNASRC to AGND. This inductor sets the real part of the input impedance at LNAIN, allowing for a more flexible input impedance match, such as a typical PCB trace antenna. A nominal value for this inductor with a 50Ω input impedance is 15nH, but is affected by PCB trace. See the *Typical Operating Characteristics* for the relationship between the inductance and the LNA input impedance.

The AGC circuit monitors the RSSI output. When the RSSI output reaches 2.05V, which corresponds to an RF input level of approximately -57dBm, the AGC switches on the LNA gain reduction resistor. The resistor reduces the LNA gain by 35dB, thereby reducing the RSSI output by about 500mV. The LNA resumes high-gain mode when the RSSI level drops back below 1.45V (approximately -65dBm at RF input) for 150ms. The AGC has a hysteresis of ~8dB. With the AGC func-

tion, the MAX1473 can reliably produce an ASK output for RF input levels up to 0dBm with a modulation depth of 18dB.

The LC tank filter connected to LNAOUT comprises L3 and C2 (see the *Typical Application Circuit*). Select L3 and C2 to resonate at the desired RF input frequency. The resonant frequency is given by:

$$f = \frac{1}{2\pi\sqrt{L_{TOTAL} \times C_{TOTAL}}}$$

where:

LTOTAL = L3 + LPARASITICS

CTOTAL = C2 + CPARASITICS

LPARASITICS and CPARASITICS include inductance and capacitance of the PCB traces, package pins, mixer input impedance, LNA output impedance, etc. These parasitics at high frequencies cannot be ignored, and can have a dramatic effect on the tank filter center frequency. Lab experimentation should be done to optimize the center frequency of the tank.

Mixer

A unique feature of the MAX1473 is the integrated image rejection of the mixer. This device eliminates the need for a costly front-end SAW filter for most applications. Advantages of not using a SAW filter are increased sensitivity, simplified antenna matching, less board space, and lower cost.

The mixer cell is a pair of double balanced mixers that perform an IQ downconversion of the RF input to the 10.7MHz IF from a low-side injected LO (i.e., $f_{LO} = f_{RF} - f_{IF}$). The image-rejection circuit then combines these signals to achieve a minimum 45dB of image rejection over the full temperature range. Low-side injection is required due to the on-chip image rejection architecture. The IF output is driven by a source-follower biased to create a driving impedance of 330Ω ; this provides a good match to the off-chip 330Ω ceramic IF filter. The voltage conversion gain is approximately 13dB when the mixer is driving a 330Ω load.

The IRSEL pin is a logic input that selects one of the three possible image-rejection frequencies. When $V_{IRSEL} = 0V$, the image rejection is tuned to 315MHz. $V_{IRSEL} = V_{DD}/2$ tunes the image rejection to 375MHz, and when $V_{IRSEL} = V_{DD}$, the image rejection is tuned to 433MHz. The IRSEL pin is internally set to $V_{DD}/2$ (image rejection at 375MHz) when it is left unconnected, thereby eliminating the need for an external $V_{DD}/2$ voltage.

Phase-Locked Loop

The PLL block contains a phase detector, charge pump/integrated loop filter, VCO, asynchronous 64x clock divider, and crystal oscillator driver. Besides the crystal, this PLL does not require any external components. The VCO generates a low-side local oscillator (LO). The relationship between the RF, IF, and reference frequencies is given by:

 $f_{REF} = (f_{RF} - f_{IF})/(32 \times M)$

where:

M = 1 (VXTALSEL = VDD) or 2 (VXTALSEL = 0V)

To allow the smallest possible IF bandwidth (for best sensitivity), the tolerance of the reference must be minimized.

Intermediate Frequency/RSSI

The IF section presents a differential 330Ω load to provide matching for the off-chip ceramic filter. The six internal AC-coupled limiting amplifiers produce an overall gain of approximately 65dB, with a bandpass filter-type response centered near the 10.7MHz IF frequency with a 3dB bandwidth of approximately 11.5MHz. The RSSI circuit demodulates the IF by producing a DC output proportional to the log of the IF signal level, with a slope of approximately 14.2mV/dB (see the *Typical Operating Characteristics*).

The AGC circuit monitors the RSSI output. When the RSSI output reaches 2.05V, which corresponds to an RF input level of approximately -57dBm, the AGC switches on the LNA gain reduction resistor. The resistor reduces the LNA gain by 35dB, thereby reducing the RSSI output by about 500mV. The LNA resumes high-gain mode when the RSSI level drops back below 1.45V (approximately -65dBm at RF input) for 150ms. The AGC has a hysteresis of ~8dB. With the AGC function, the MAX1473 can reliably produce an ASK output for RF input levels up to 0dBm with modulation depth of 18dB.

_Applications Information

Crystal Oscillator

The XTAL oscillator in the MAX1473 is designed to present a capacitance of approximately 3pF between the XTAL1 and XTAL2. If a crystal designed to oscillate with a different load capacitance is used, the crystal is pulled away from its stated operating frequency, introducing an error in the reference frequency. Crystals designed to operate with higher differential load capacitance always pull the reference frequency higher. For example, a 4.7547MHz crystal designed to operate with a 10pF load capacitance oscillates at 4.7563MHz with the MAX1473, causing the receiver to be tuned to 315.1MHz rather than 315.0MHz, an error of about 100kHz, or 320ppm.

Table 1. Component Values for Typical Application Circuit

| COMPONENT | VALUE FOR 433MHz RF | VALUE FOR 315MHz RF | DESCRIPTION |
|-----------|-------------------------|------------------------|-------------------------|
| C1 | 100pF | 100pF | 5% |
| C2 | 2.7pF | 4.7pF | ± 0.1pF |
| C3 | 100pF | 100pF | 5% |
| C4 | 100pF | 100pF | 5% |
| C5 | 1500pF | 1500pF | 10% |
| C6 | 220pF | 220pF | 5% |
| C7 | 470pF | 470pF | 5% |
| C8 | 0.47µF | 0.47µF | 20% |
| C9 | 220pF | 220pF | 10% |
| C10 | 0.01µF | 0.01µF | 20% |
| C11 | 0.01µF | 0.01μF | 20% |
| C12 | 15pF | 15pF | Depends on XTAL |
| C13 | 15pF | 15pF | Depends on XTAL |
| L1 | 56nH | 110nH | TOKO LL1608-FH |
| L2 | 15nH | 15nH | Murata LQP11A |
| L3 | 15nH | 27nH | Murata LQP11A |
| R1 | 5kΩ | 5k Ω | 5% |
| X1 | 6.6128MHz or 13.2256MHz | 4.7547MHz or 9.5094MHz | _ |
| X2 | 10.7MHz ceramic filter | 10.7MHz ceramic filter | Murata SFECV10.7 series |

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In actuality, the oscillator pulls every crystal. The crystal's natural frequency is really below its specified frequency, but when loaded with the specified load capacitance, the crystal is pulled and oscillates at its specified frequency. This pulling is already accounted for in the specification of the load capacitance.

Additional pulling can be calculated if the electrical parameters of the crystal are known. The frequency pulling is given by:

$$f_p = \frac{C_m}{2} \left(\frac{1}{C_{case + C_{load}}} - \frac{1}{C_{case + C_{spec}}} \right) \times 10^6$$

fp is the amount the crystal frequency pulled in ppm.

C_m is the motional capacitance of the crystal.

C_{case} is the case capacitance.

C_{spec} is the specified load capacitance.

Cload is the actual load capacitance.

When the crystal is loaded as specified, i.e., Cload = C_{spec}, the frequency pulling equals zero.

Data Filter

The data filter is implemented as a 2nd-order lowpass Sallen-Key filter. The pole locations are set by the combination of two on-chip resistors and two external capacitors. Adjusting the value of the external capacitors changes the corner frequency to optimize for different data rates. The corner frequency should be set to approximately 1.5 times the fastest expected data rate from the transmitter. Keeping the corner frequency near the data rate rejects any noise at higher frequencies, resulting in an increase in receiver sensitivity.

The configuration shown in Figure 1 can create a Butterworth or Bessel response. The Butterworth filter offers a very flat amplitude response in the passband and a rolloff rate of 40dB/decade for the two-pole filter. The Bessel filter has a linear phase response, which works well for filtering digital data. To calculate the value of C5 and C6, use the following equations along with the coefficients in Table 2:

C5 =
$$\frac{b}{a(100k)(\pi)(f_c)}$$
C6 =
$$\frac{a}{4(100k)(\pi)(f_c)}$$

$$C6 = \frac{a}{4(100k)(\pi)(f_C)}$$

where f_C is the desired 3dB corner frequency.

For example, choose a Butterworth filter response with a corner frequency of 5kHz:

C5 =
$$\frac{1.000}{(1.414)(100k\Omega)(3.14)(5kHz)} \approx 450pF$$

Choosing standard capacitor values changes C5 to 470pF and C6 to 220pF, as shown in the Typical Application Circuit.

Data Slicer

The purpose of the data slicer is to take the analog output of the data filter and convert it to a digital signal. This is achieved by using a comparator and comparing the analog input to a threshold voltage. One input is supplied by the data filter output. Both comparator inputs are accessible off chip to allow for different methods of generating the slicing threshold, which is applied to the second comparator input.

The suggested data slicer configuration uses a resistor (R1) connected between DSN and DSP with a capacitor (C4) from DSN to DGND (Figure 2). This configuration averages the analog output of the filter and sets the threshold to approximately 50% of that amplitude. With this configuration, the threshold automatically adjusts as the analog signal varies, minimizing the possibility for errors in the digital data. The sizes of R1 and C4 affect how fast the threshold tracks to the analog amplitude. Be sure to keep the corner frequency of the RC circuit much lower than the lowest expected data rate.

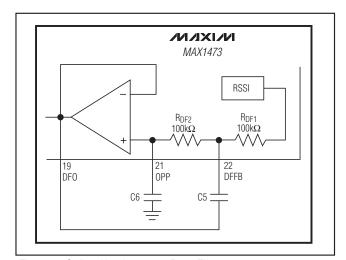


Figure 1. Sallen-Key Lowpass Data Filter

Table 2. Coefficents to Calculate C5 and C6

| FILTER TYPE | а | b |
|-------------------------|--------|-------|
| Butterworth (Q = 0.707) | 1.414 | 1.000 |
| Bessel (Q = 0.577) | 1.3617 | 0.618 |

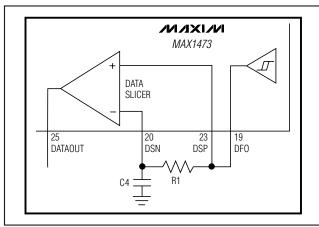


Figure 2. Generating Data Slicer Threshold

Note that a long string of zeros or 1's can cause the threshold to drift. This configuration works best if a coding scheme, such as Manchester coding, which has an equal number of zeros and 1's, is used.

To prevent continuous toggling of DATAOUT in the absence of an RF signal due to noise, hysteresis can be added to the data slicer as shown in Figure 3.

Peak Detector

The peak detector output (PDOUT), in conjunction with an external RC filter, creates a DC output voltage equal to the peak value of the data signal. The resistor provides a path for the capacitor to discharge, allowing the peak detector to dynamically follow peak changes of the data filter output voltage. For faster receiver startup, the circuit shown in Figure 4 can be used.

Layout Considerations

A properly designed PCB is an essential part of any RF/microwave circuit. On high-frequency inputs and outputs, use controlled-impedance lines and keep them as short as possible to minimize losses and radiation. At high frequencies, trace lengths that are on the order of $\lambda/10$ or longer act as antennas.

Keeping the traces short also reduces parasitic inductance. Generally, 1in of a PCB trace adds about 20nH of parasitic inductance. The parasitic inductance can have a dramatic effect on the effective inductance of a passive component. For example, a 0.5in trace connecting a 100nH inductor adds an extra 10nH of inductance or 10%.

To reduce the parasitic inductance, use wider traces and a solid ground or power plane below the signal traces. Also, use low-inductance connections to ground on all GND pins, and place decoupling capacitors close to all power-supply pins.

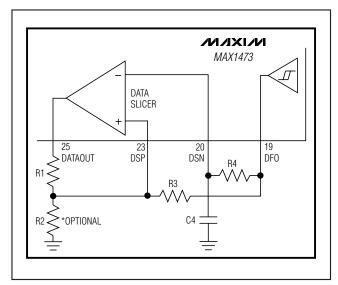


Figure 3. Generating Data Slicer Hysteresis

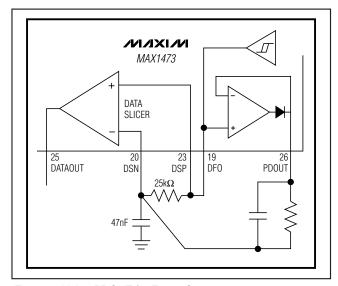


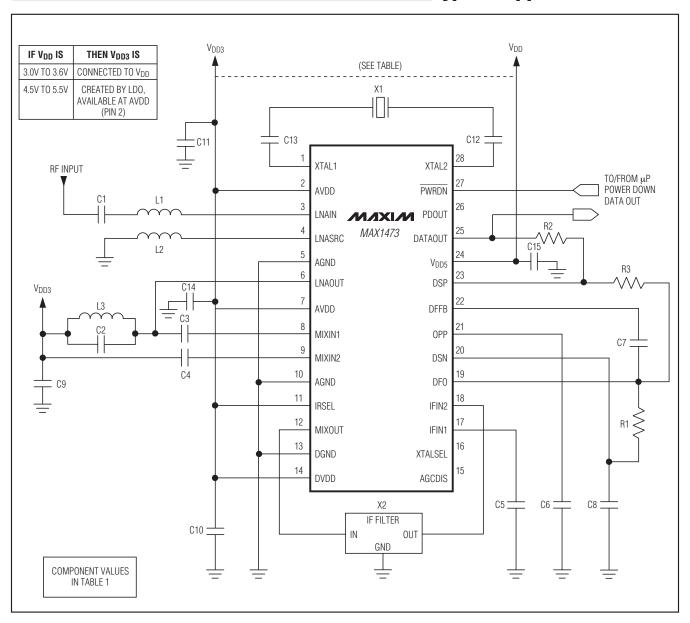
Figure 4. Using PDOUT for Faster Startup

Chip Information

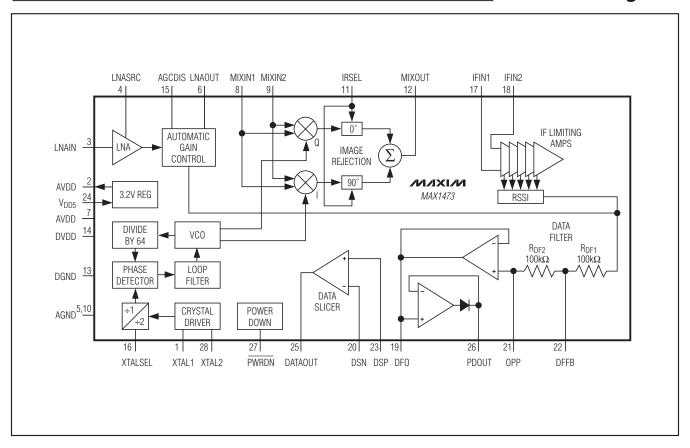
PROCESS: CMOS

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Typical Application Circuit



Functional Diagram



Package Information

For the latest package outline information and land patterns (footprints), go to **www.maxim-ic.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

| PACKAGE TYPE | PACKAGE CODE | OUTLINE NO. | LAND PATTERN NO. |
|----------------|--------------|----------------|---------------------|
| 28 TSSOP | U28+1 | <u>21-0066</u> | <u>90-0171</u> |
| 32 Thin QFN-EP | T3255+3 | <u>21-0140</u> | <u>90-0001</u> |

_Revision History

| REVISION NUMBER | REVISION DATE | DESCRIPTION | PAGES CHANGED |
|--------------------|------------------|--|------------------------------|
| 4 | 5/10 | Added lead-free parts and exposed pad in <i>Ordering Information</i> and <i>Pin Description</i> tables | 1, 8 |
| 5 | 1/11 | Updated Absolute Maximum Ratings, AC Electrical Characteristics, Pin Description, Layout Considerations, Typical Application Circuit, Functional Diagram, and Package Information; added Voltage Regulator section to the Detailed Description section | 2, 3, 4, 8, 9, 12, 13, 14 |

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